

ABSTRACT OF THE DISCLOSURE

The present invention relates to a lead-free bump with suppressed formation of voids, obtained by reflowing a plated
5 film of Sn-Ag solder alloy having an adjusted Ag content, and a method of forming the lead-free bump. The lead-free bump of the present invention is obtained by forming an Sn-Ag alloy film having a lower Ag content than that of an Sn-Ag eutectic composition by plating and reflowing the plated alloy film.

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